

[COOLING SYSTEM]

Abstract

A cooling system for cooling an interface card is provided. The cooling system comprises a thermal conductive housing wrapping around a carrier of the interface card and the electronic devices thereon. A pair of fans are set up on the housing to provide a flow of air inside the space between the housing and the carrier so that the heat generated by the operating devices are rapidly carried away. In addition, a fin type heat sink can be incorporated into the space between the housing and the electronic devices to increase the amount of heat transferred away from the operating devices.